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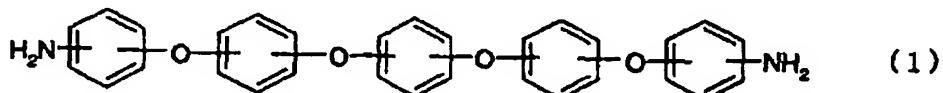
AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings, of claims in the application:

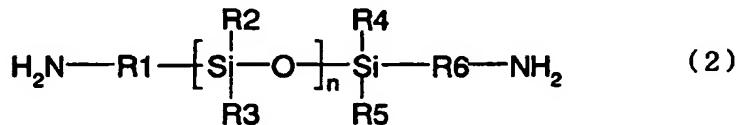
LISTING OF CLAIMS:

1. - 7. (Canceled)

8. (New) An adhesive resin comprising a polyimide resin obtained by reacting a diamine component containing a diamine represented by the following formula (1) as an essential component with a tetracarboxylic dianhydride component,

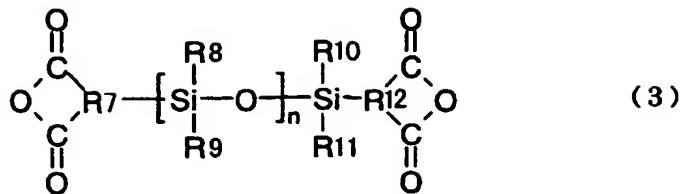


wherein the diamine component further comprises a diamine represented by the following formula (2) as a diamine component,



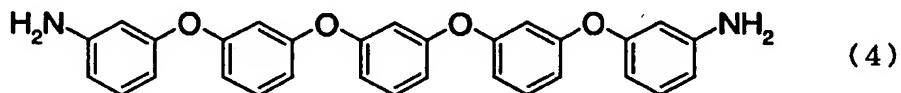
(wherein R1 and R6 are divalent aliphatic groups having 1 to 4 carbon atoms or aromatic groups; R2 to R5 are monovalent aliphatic groups or aromatic groups; and n is an integer of 0 to 20)

and/or the tetracarboxylic dianhydride component further comprises a tetracarboxylic dianhydride represented by the following formula (3) as the tetracarboxylic dianhydride component,



(wherein R7 and R12 are trivalent aliphatic groups or aromatic groups; R8 to R11 are monovalent aliphatic groups or aromatic groups; the carbon skeleton of the acid anhydride structure is a 5- or 6-membered ring; and n is an integer of 0 to 20).

9. (New) The adhesive resin according to Claim 8, wherein the diamine represented by the formula (1) comprises a diamine represented by the following formula (4)



10. (New) The adhesive resin according to Claim 8 comprising a thermosetting resin except a polyimide resin.

11. (New) The adhesive resin according to Claim 8, wherein the thermosetting resin comprises an epoxy resin, and the adhesive resin further comprises an epoxy resin-curing agent.

12. (New) The adhesive resin according to Claim 8 comprising inorganic filler.

13. (New) A film adhesive comprising the adhesive resin according to Claim 8.

14. (New) A semiconductor device wherein a semiconductor element is attached to a support by the film adhesive according to Claim 6.